

Abstract

Method of processing a workpiece, and a work carrier, in particular of porous ceramic

Explained, inter alia, is a method in which a workpiece (52) to be processed is fastened to a work carrier (10) by means of a solid (62). The work carrier (10) is made of a porous material, e.g. of porous ceramic. This processing method permits simple manipulation of the wafer during the processing. In addition, the workpiece (52) can be easily separated from the work carrier (10) using a solvent.

List of designations

10	Work carrier
DM1	Diameter
12	Side
13	Flat
14 to 22	Pore
D1 to D3	Thickness
24, 26	Pore passage
30	Top side
32	Rear side
50	Holding device
52, 52a, 52b	Semiconductor wafer
54	Base plate
56	Holding ring
58	Chamber
60	Suction passage
62	Adhesive
64	Arrow
70	CMP machine
72	Holding ring
74	Base plate
76	Grinding tool
80	Drive shank
81	Direction of rotation arrow
82	Grinding disk
84	Polishing cloth
90	Solvent
92	Tank
94	Base
96	Through passage
98	Holding ring

100	Chamber
102, 104	Arrow